

# 2.2A, 400V - 1000V Glass Passivated Bridge Rectifier

#### **FEATURES**

- Glass passivated junction
- Ideal for automated placement
- Reliable low cost construction utilizing molded plastic technique
- High surge current capability
- UL Recognized File # E-326854
- Compliant to RoHS directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21

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- Switching mode power supply (SMPS)
- Adapters
- TV
- Monitor

### **MECHANICAL DATA**

- · Case: YBS
- Molding compound meets UL 94V-0 flammability rating
- Moisture sensitivity level: level 1, per J-STD-020
- Packing code with suffix "G" means green compound (halogen-free)
- Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 1A whisker test
- Polarity: As marked
- Weight: 0.22g (approximately)

KEY PARAMETERS					
PARAMETER	VALUE	UNIT			
I <sub>F(AV)</sub>	2.2	Α			
$V_{RRM}$	400 - 1000	V			
I <sub>FSM</sub>	90	Α			
$T_{JMAX}$	150	°C			
Package	YBS				
Configuration	Quad				











**YBS** 





ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	SYMBOL	YBS 2204G	YBS 2205G	YBS 2206G	YBS 2207G	UNIT
Marking code on the device		YBS2204G				
Repetitive peak reverse voltage	$V_{RRM}$	400	600	800	1000	V
Reverse voltage, total rms value	$V_{R(RMS)}$	280	420	560	700	V
Forward current	I <sub>F(AV)</sub>		2	.2	·	Α
Surge peak forward current, 8.3 ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>		9	0		Α
I <sup>2</sup> t value (of a surge on-state current)	l <sup>2</sup> t	33		A <sup>2</sup> s		
Junction temperature	TJ	-55 to +150			°C	
Storage temperature	T <sub>STG</sub>		-55 to	+150		°C

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THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	R <sub>OJL</sub>	24	°C/W		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	61	°C/W		
Junction-to-case thermal resistance	R <sub>eJC</sub>	11	°C/W		

Thermal Performance Note: Units mounted on recommended PCB (16mm x 16mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT	
	I <sub>F</sub> = 1.1A, T <sub>J</sub> = 25°C		0.86	0.92	V	
[ [ ] [ ] [ ] [ ] [ ] [ ] [ ] [ ] [ ] [	I <sub>F</sub> = 2.2A, T <sub>J</sub> = 25°C	V <sub>F</sub>	0.91	0.97	V	
Forward voltage (1)	I <sub>F</sub> = 1.1A, T <sub>J</sub> = 125°C		0.73	0.9	V	
	I <sub>F</sub> = 2.2A, T <sub>J</sub> = 125°C		0.78	0.95	V	
D	T <sub>J</sub> = 25°C		0.2	5	μA	
Reverse current @ rated V <sub>R</sub> <sup>(2)</sup>	T <sub>J</sub> = 125°C	l <sub>R</sub>	35	100	μA	
Junction capacitance	1 MHz, V <sub>R</sub> =4.0V	CJ	70	90	pF	
Reverse recovery time	I <sub>F</sub> =0.5A , I <sub>R</sub> =1.0A I <sub>RR</sub> =0.25A	t <sub>rr</sub>	2400	4000	ns	

#### Notes:

- 1. Pulse test with PW=0.3 ms
- 2. Pulse test with PW=30 ms

ORDERING INFORMATION						
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING		
YBS22xxG (Note 1, 2)	RA	G	YBS	3,000 / 13" Plastic reel		

#### Notes:

- 1. "xx" defines voltage from 400V (YBS2204G) to 1000V (YBS2207G)
- 2. Whole series with green compound (halogen-free)

EXAMPLE						
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION		
YBS2207G RAG	YBS2207G	RA	G	Green compound		

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### **CHARACTERISTICS CURVES**

(T<sub>A</sub> = 25°C unless otherwise noted)

Fig.1 Forward Current Derating Curve

AVERAGE FORWARD CURRENT (A)

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4

4

4

5

6

6

90

120

150

**Fig.2 Typical Junction Capacitance** 

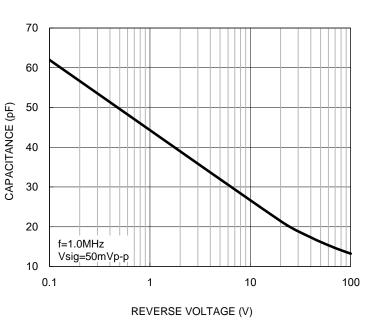
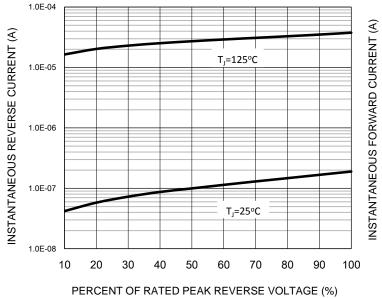
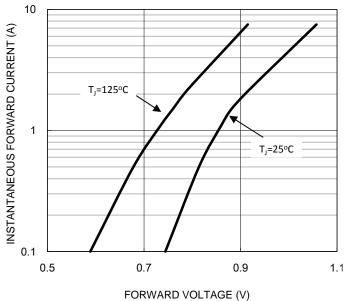


Fig.3 Typical Reverse Characteristics

LEAD TEMPERATURE (°C)



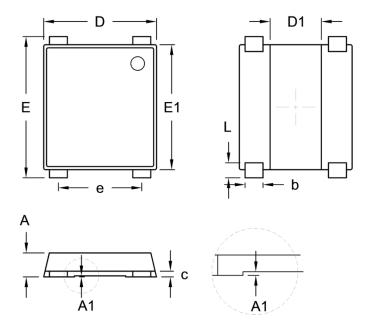
**Fig.4 Typical Forward Characteristics** 





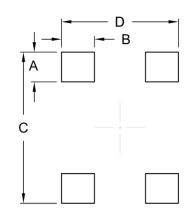
## PACKAGE OUTLINE DIMENSIONS (Unit: Millimeters)

YBS



DIM.	Unit	(mm)	Unit (inch)	
DIN.	Min.	Max.	Min.	Max.
Α	1.30	1.50	0.051	0.059
A1	0.04	0.08	0.002	0.003
b	0.95	1.15	0.037	0.045
С	0.27	0.40	0.011	0.016
D	6.50	6.70	0.256	0.264
D1	2.90	3.10	0.114	0.122
E	7.90	8.60	0.311	0.339
E1	7.20	7.40	0.283	0.291
е	5.00	5.20	0.197	0.205
L	0.70	1.05	0.028	0.041

### **SUGGESTED PAD LAYOUT**



Symbol	Unit (mm)	Unit (inch)
Α	1.80	0.070
В	2.00	0.078
С	9.15	0.360
D	7.10	0.279

## **MARKING DIAGRAM**



P/N = Marking Code YW = Date Code F = Factory Code



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